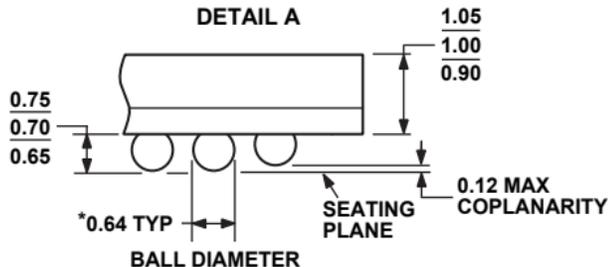
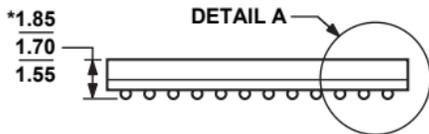
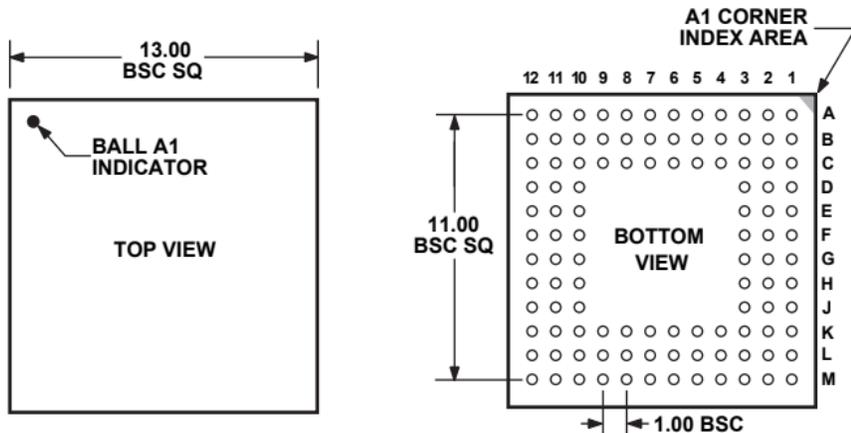


**108-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-108-2)**

Dimensions shown in millimeters



*COMPLIANT WITH JEDEC STANDARDS MO-192-AAD-1 WITH THE EXCEPTION OF PACKAGE HEIGHT AND BALL DIAMETER.